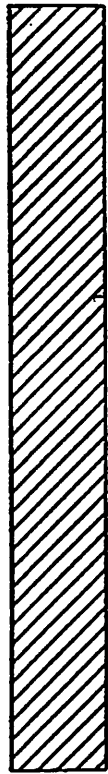


CHIP CONSTRUCTION

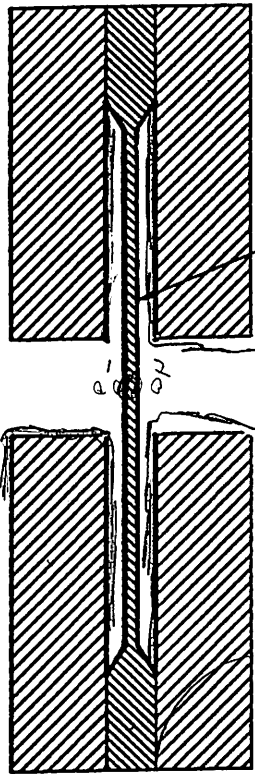


SILICON
WAFER
THICKNESS

IDEAL
ELASTIC
ELEMENT

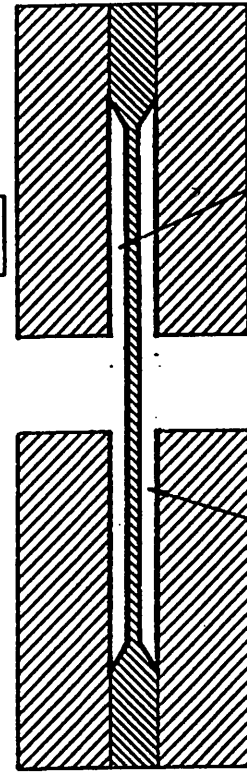


ETCHED SILICON
DIAPHRAGM



3 LAYER
SILICON GLASS DIE

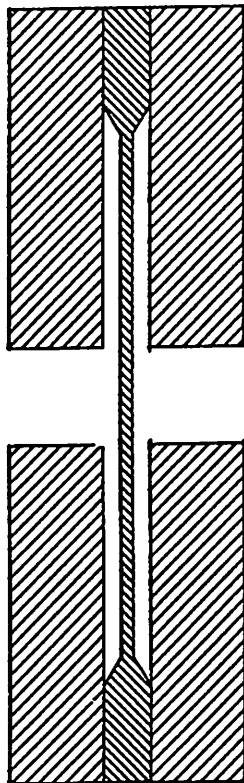
2-12
MICRONS



(2) SETS OF DIFFERENTIAL
CAPACITOR PLATES
ALUMINUM ON GLASS

C1

C2



P2
C1
+

P1
C2
-

CAPACITANCE = AREA OF PLATES

DISTANCE BETWEEN
PLATES

GAPS = 4-5 MICRONS

DIAPHRAGM
TRAVEL = 1-2 MICRONS